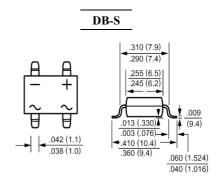


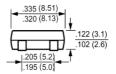
FEATURES

- · Glass passivated chip junction
- \cdot Low forward voltage drop
- \cdot High surge overload rating of 50 Amperes peak
- \cdot Ideal for printed circuit board
- High temperature soldering guaranteed: 260°C for 10 seconds

MECHANICAL DATA

Case: Molded plastic, DB-S Epoxy: UL 94V-O rate flame retardant Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed Mounting position: Any Weight: 0.02ounce, 0.4gram





Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified. Single phase, half wave, $60H_Z$, resistive or inductive load. For capacitive load, derate current by 20%.

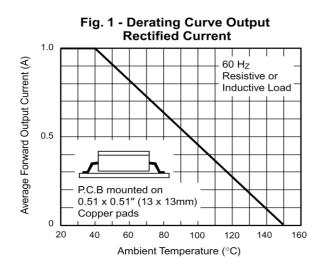
	Symbols	DF005S	DF01S	DF02S	DF04S	DF06S	DF08S	DF10S	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T _A =40 (Note 2)	I _(AV)				1.5	•		•	Amp
Peak Forward Surge Current,									
8.3ms single half-sine-wave	I _{FSM}	I _{FSM} 50							Amp
superimposed on rated load (JEDEC method)									
Maximum Forward Voltage at 1.0A DC and 25	V _F	1.1							Volts
Maximum Reverse Current at T _A =25	T				5.0				
at Rated DC Blocking Voltage T _A =125	I _R	500							uAmp
Typical Junction Capacitance (Note 1)	CJ	25							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	40							/W
Typical Thermal Resistance (Note 2)	R _{0JL}	15							/W
Operating and Storage Temperature Range	T _J , Tstg				-55 to +15	0			

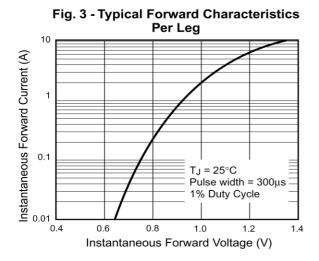
NOTES:

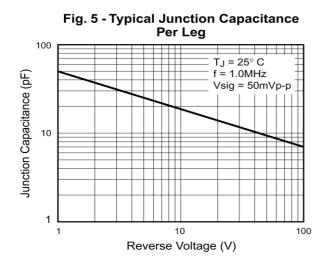
1- Measured at 1 MH_Z and applied reverse voltage of 4.0 VDC.

2- Units mounted on P.C.B. with 0.5 x 0.5" (13 x 13mm) copper pads









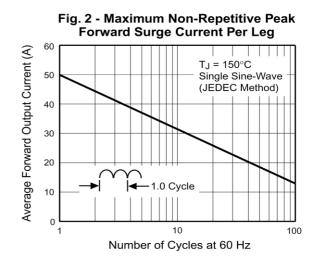


Fig. 4 - Typical Reverse Leakage Characteristics Per Leg

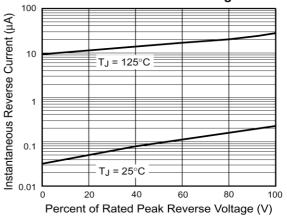


Fig. 6 - Typical Transient Thermal Impedance

